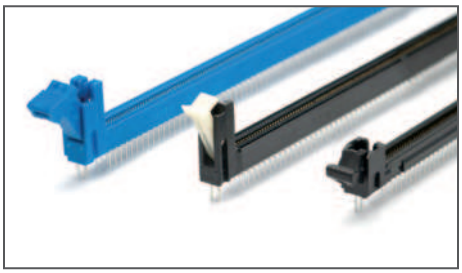
DDR4 DIMM Sockets, Halogen-free

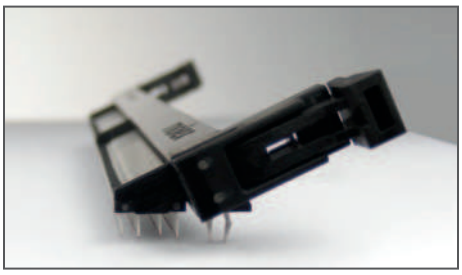
Angled, Ultra Low-Profile, Aerodynamic and Standard versions

molex®

Angled, Ultra Low-profile, Aerodynamic and Standard DDR4 DIMM sockets combine excellent performance with maximum space-savings and assembly processing for high-speed data and networking applications



From left: Standard, Aerodynamic and Ultra Low-Profile DDR4 DIMM Sockets



25°-Angled DDR4 DIMM Socket

Features and Benefits

25° angle inclination to the horizontal (Angled version)	Gives up to 45% vertical space savings over Standard vertical versions
Ultra-low seating plane of 1.10mm (Ultra low-profile version)	Frees up vertical module space to allow use of high-density DIMMs while maintaining the same design height; Enables the use of very low-profile modules with seating heights below 2.80mm (maximum) in ATCA* blade systems
Lower current of 0.75A per terminal compared to 1.0A for ULP DDR3 DIMM versions	For bigger energy cost savings
Streamlined housing and latch design (Aerodynamic series)	Minimizes trapping of hot air around high-density memory modules during operation
Metal-reinforced latch tower housing (Angled, Aerodynamic and Standard series)	Prevents cleavage or separation of tower bridge due to wear and tear
Multiple soldertail length options available for Through-hole and Press-fit sockets (Aerodynamic and Standard series)	To suit various PCB thicknesses
Flush soldertail design for SMT socket (Standard series only)	Minimizes accidental damage to terminals due to bending
Anti-stubbing mating contacts (All series)	Provide smooth module lead-in and contact grip during insertion

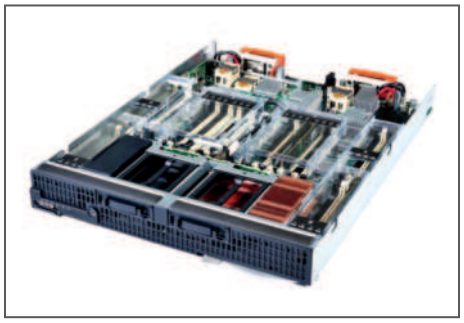
Applications

Data/Computing

- High-end computing
- Personal computers
- RAID / Storage

Telecommunications/Networking

- Infrastructure
- Networking



Servers



Data Centers

Product Name

Product Description, or series list

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Specifications

Reference Information

Packaging: Tray
UL File No.: E29179 (78860)
CSA File No.: TBA
Use With: JEDEC MO-309 memory modules
Designed In: Millimeter
RoHS: Yes
Halogen Free: Yes
Glow Wire Compliant: No

Electrical

Voltage (max.): 29V AC (RMS)/DC
Current (max.): 0.75A per pin
Low Level Contact Resistance (max.):
12 (78860); 20 (151080); 10 milliohms (others)
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance (min.): 1 megohm

Mechanical

Module Insertion Force (with latches): 106.8N max
Module Rip-out Force (min.): 9.10kgf
Compliant-pin Insertion Force to PCB (single):
4.50kgf max.(78731, 151024)
Compliant-pin Retention Force to PCB (single):
0.30kg min. (78731, 151024)
Module Unmating Force: 2.02kgf
Terminal Retention Force (min.):
300gf (per pin);
13.3N (per forklock for 78860, 151016 only)
Latch Actuation Force (max.): 3.50kgf per latch
Durability: 25 cycles

Physical

Housing: Halogen-free, high-temperature Nylon,
glass-filled, UL94V-0 (both socket and latch)
Contact: Copper Alloy
Plating: Refer to Sales Drawing
PCB Thickness: Refer to Sales Drawings
Operating Temperature: -55 to +85°C

Ordering Information

Series No.	Style	Termination
151080	Angled 25°	Through-hole
78860	Ultra Low-Profile	Through-hole
151016	Aerodynamic	Through-hole
151024		Press-fit
78726	Standard	Through-hole
78730		SMT
78731		Press-fit

www.molex.com/link/ddr4.html

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